

<b>Notice of References Cited</b>	Application/Control No. 10/764,023		Applicant(s)/Patent Under Reexamination PARK ET AL.	
	Examiner Jacques M. Saint-Surin		Art Unit 2856	Page 1 of 1

**U.S. PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
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	B	US-4,312,228	01-1982	Wohltjen, Henry	73/597
	C	US-6,668,618	12-2003	Larson et al.	73/24.01
	D	US-6,651,488	11-2003	Larson et al.	73/61.62
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	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

**FOREIGN PATENT DOCUMENTS**

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	N					
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**NON-PATENT DOCUMENTS**

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	US 2002/0017138 A1, Ueyanagi et al. Semiconductor sensor chip and method for producing the chip, and semiconductor sensor and package for assembling the sensor.
	V	
	W	
	X	

\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.